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FAIRCHILD SEMICONDUCTOR®

January 2008

74AC125, 74ACT125
Quad Buffer with 3-STATE Outputs

Features

- I_{CC} reduced by 50%
- Outputs source/sink 24mA
- ACT125 has TTL-compatible outputs

General Description

The AC/ACT125 contains four independent non-inverting buffers with 3-STATE outputs.

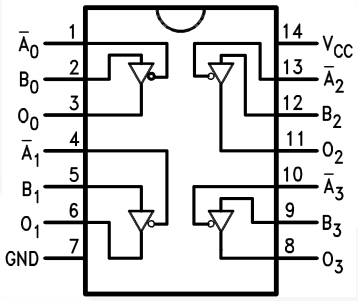
Ordering Information

Order Number	Package Number	Package Description
74AC125SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74AC125SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC125MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC125PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74ACT125SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74ACT125SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACT125MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACT125PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

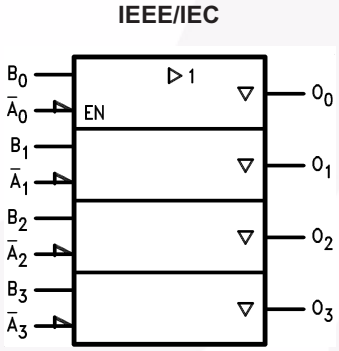
Device also available in Tape and Reel. Specify by appending suffix letter “X” to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



Logic Symbol



Pin Description

Pin Names	Description
$\overline{A}_n$, B_n	Inputs
O_n	Outputs

Function Table

Inputs		Output
A_n	B_n	O_n
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level, L = LOW Voltage Level
Z = HIGH Impedance, X = Immaterial

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	–0.5V to +7.0V
I_{IK}	DC Input Diode Current	
	$V_I = –0.5V$	–20mA
	$V_I = V_{CC} + 0.5$	+20mA
V_I	DC Input Voltage	–0.5V to V_{CC} + 0.5V
I_{OK}	DC Output Diode Current	
	$V_O = –0.5V$	–20mA
	$V_O = V_{CC} + 0.5V$	+20mA
V_O	DC Output Voltage	–0.5V to V_{CC} + 0.5V
I_O	DC Output Source or Sink Current	±50mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current per Output Pin	±50mA
T_{STG}	Storage Temperature	–65°C to +150°C
T_J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	
	AC	2.0V to 6.0V
	ACT	4.5V to 5.5V
V_I	Input Voltage	0V to V_{CC}
V_O	Output Voltage	0V to V_{CC}
T_A	Operating Temperature	–40°C to +85°C
$\Delta V / \Delta t$	Minimum Input Edge Rate, AC Devices:	125mV/ns
	V_{IN} from 30% to 70% of V_{CC}, V_{CC} @ 3.3V, 4.5V, 5.5V	
$\Delta V / \Delta t$	Minimum Input Edge Rate, ACT Devices:	125mV/ns
	V_{IN} from 0.8V to 2.0V, V_{CC} @ 4.5V, 5.5V	

DC Electrical Characteristics for AC

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C	T_A = –40°C to +85°C		Units
				Typ.	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	3.0	V_{OUT} = 0.1V or V_{CC} – 0.1V	1.5	2.1	2.1	V
		4.5		2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V_{IL}	Maximum LOW Level Input Voltage	3.0	V_{OUT} = 0.1V or V_{CC} – 0.1V	1.5	0.9	0.9	V
		4.5		2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V_{OH}	Minimum HIGH Level Output Voltage	3.0	I_{OUT} = –50µA	2.99	2.9	2.9	V
		4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL}$ or V_{IH}, I_{OH} = –12mA		2.56	2.46	
		4.5	$V_{IN} = V_{IL}$ or V_{IH}, I_{OH} = –24mA		3.86	3.76	
		5.5	$V_{IN} = V_{IL}$ or V_{IH}, I_{OH} = –24mA(1)		4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	3.0	I_{OUT} = 50µA	0.002	0.1	0.1	V
		4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL}$ or V_{IH}, I_{OL} = 12mA		0.36	0.44	
		4.5	$V_{IN} = V_{IL}$ or V_{IH}, I_{OL} = 24mA		0.36	0.44	
		5.5	$V_{IN} = V_{IL}$ or V_{IH}, I_{OL} = 24mA(1)		0.36	0.44	
I_{IN}(3)	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	µA
I_{OZ}	Maximum 3-STATE Current	5.5	V_I (OE) = V_{IL}, V_{IH}, $V_I = V_{CC}$, V_{GND}, $V_O = V_{CC}$, GND		±0.25	±2.5	µA
I_{OLD}	Minimum Dynamic Output Current(2)	5.5	V_{OLD} = 1.65V Max.			75	mA
I_{OHD}		5.5	V_{OHD} = 3.85V Min.			–75	mA
I_{CC}(3)	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	µA

Notes:

1. All outputs loaded; thresholds on input associated with output under test.
2. Maximum test duration 2.0ms, one output loaded at a time.
3. I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC}.

DC Electrical Characteristics for ACT

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C	T_A = –40°C to +85°C		Units
				Typ.	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	4.5	V_{OUT} = 0.1V or V_{CC} – 0.1V	1.5	2.0	2.0	V
		5.5		1.5	2.0	2.0	
V_{IL}	Maximum LOW Level Input Voltage	4.5	V_{OUT} = 0.1V or V_{CC} – 0.1V	1.5	0.8	0.8	V
		5.5		1.5	0.8	0.8	
V_{OH}	Minimum HIGH Level Output Voltage	4.5	I_{OUT} = –50µA	4.49	4.4	4.4	V
		5.5		5.49	5.4	5.4	
		4.5	V_{IN} = V_{IL} or V_{IH}, I_{OH} = –24mA		3.86	3.76	
		5.5	V_{IN} = V_{IL} or V_{IH}, I_{OH} = –24mA(4)		4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	4.5	I_{OUT} = 50µA	0.001	0.1	0.1	V
		5.5		0.001	0.1	0.1	
		4.5	V_{IN} = V_{IL} or V_{IH}, I_{OL} = 24mA		0.36	0.44	
		5.5	V_{IN} = V_{IL} or V_{IH}, I_{OL}= 24mA(4)		0.36	0.44	
I_{IN}	Maximum Input Leakage Current	5.5	V_I = V_{CC}, GND		±0.1	±1.0	µA
I_{OZ}	Maximum 3-STATE Current	5.5	V_I = V_{IL}, V_{IH}; V_O = V_{CC}, GND		±0.5	±5.0	µA
I_{CCT}	Maximum I_{CC}/Input	5.5	V_I = V_{CC} – 2.1V(6)	0.6		1.5	mA
I_{OLD}	Minimum Dynamic Output Current(5)	5.5	V_{OLD} = 1.65V Max.			75	mA
I_{OHD}		5.5	V_{OHD} = 3.85V Min.			–75	mA
I_{CC}	Maximum Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND		4.0	40.0	µA

Notes:

4. All outputs loaded; thresholds on input associated with output under test.
5. Maximum test duration 2.0ms, one output loaded at a time.
6. May be measured per the JEDEC Alternate Method.

AC Electrical Characteristics for AC

Symbol	Parameter	V_{CC} (V)[7]	T_A = +25°C, C_L = 50pF			T_A = –40°C to +85°C, C_L = 50pF		Units
			Min.	Typ.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay, Data to Output	3.3	1.0	6.5	9.0	1.0	10.0	ns
		5.0	1.0	5.5	7.0	1.0	7.5	
t_{PHL}	Propagation Delay, Data to Output	3.3	1.0	6.5	9.0	1.0	10.0	ns
		5.0	1.0	5.0	7.0	1.0	7.5	
t_{PZH}	Output Enable Time	3.3	1.0	6.0	10.5	1.0	11.0	ns
		5.0	1.0	5.0	7.0	1.0	8.0	
t_{PZL}	Output Enable Time	3.3	1.0	7.5	10.0	1.0	11.0	ns
		5.0	1.0	5.5	8.0	1.0	8.5	
t_{PHZ}	Output Disable Time	3.3	1.0	7.5	10.0	1.0	10.5	ns
		5.0	1.0	6.5	9.0	1.0	9.5	
t_{PLZ}	Output Disable Time	3.3	1.0	7.5	10.5	1.0	11.5	ns
		5.0	1.0	6.5	9.0	1.0	9.5	

Note:

7. Voltage range 3.3 is 3.3V ± 0.3V. Voltage range 5.0 is 5.0V ± 0.5V.

AC Electrical Characteristics for ACT

Symbol	Parameter	V_{CC} (V)[8]	T_A = +25°C, C_L = 50pF			T_A = –40°C to +85°C, C_L = 50pF		Units
			Min.	Typ.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay, Data to Output	5.0	1.0	6.5	9.0	1.0	10.0	ns
t_{PHL}	Propagation Delay, Data to Output	5.0	1.0	7.0	9.0	1.0	10.0	ns
t_{PZH}	Output Enable Time	5.0	1.0	6.0	8.5	1.0	9.5	ns
t_{PZL}	Output Enable Time	5.0	1.0	7.0	9.5	1.0	10.5	ns
t_{PHZ}	Output Disable Time	5.0	1.0	7.0	9.5	1.0	10.5	ns
t_{PLZ}	Output Disable Time	5.0	1.0	7.5	10.0	1.0	10.5	ns

Note:

8. Voltage Range 5.0 is 5.0V ± 0.5V.

Capacitance

Symbol	Parameter	Conditions	Typ.	Units
C_{IN}	Input Capacitance	V_{CC} = OPEN	4.5	pF
C_{PD}	Power Dissipation Capacitance	V_{CC} = 5.0V	45.0	pF

Physical Dimensions

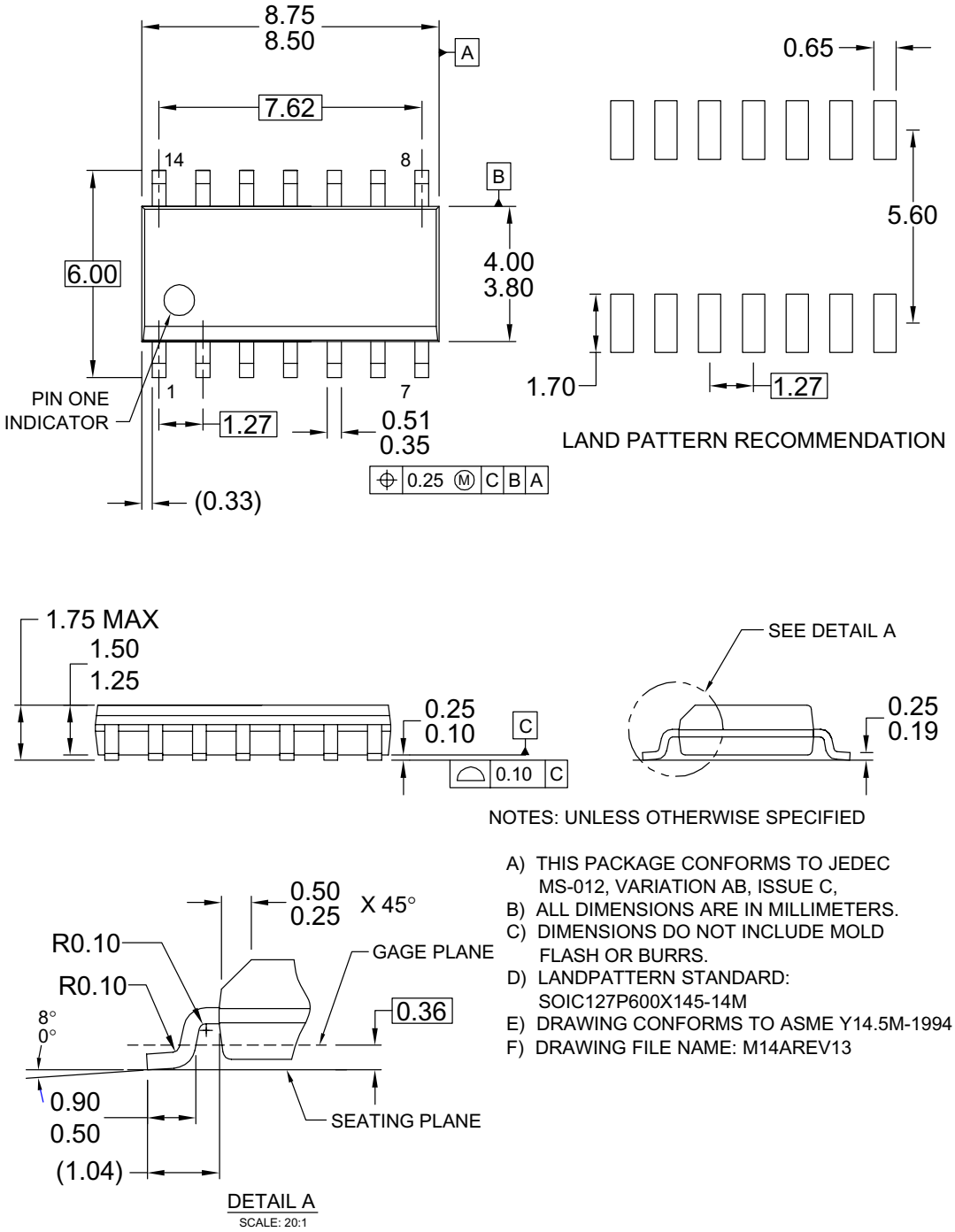


Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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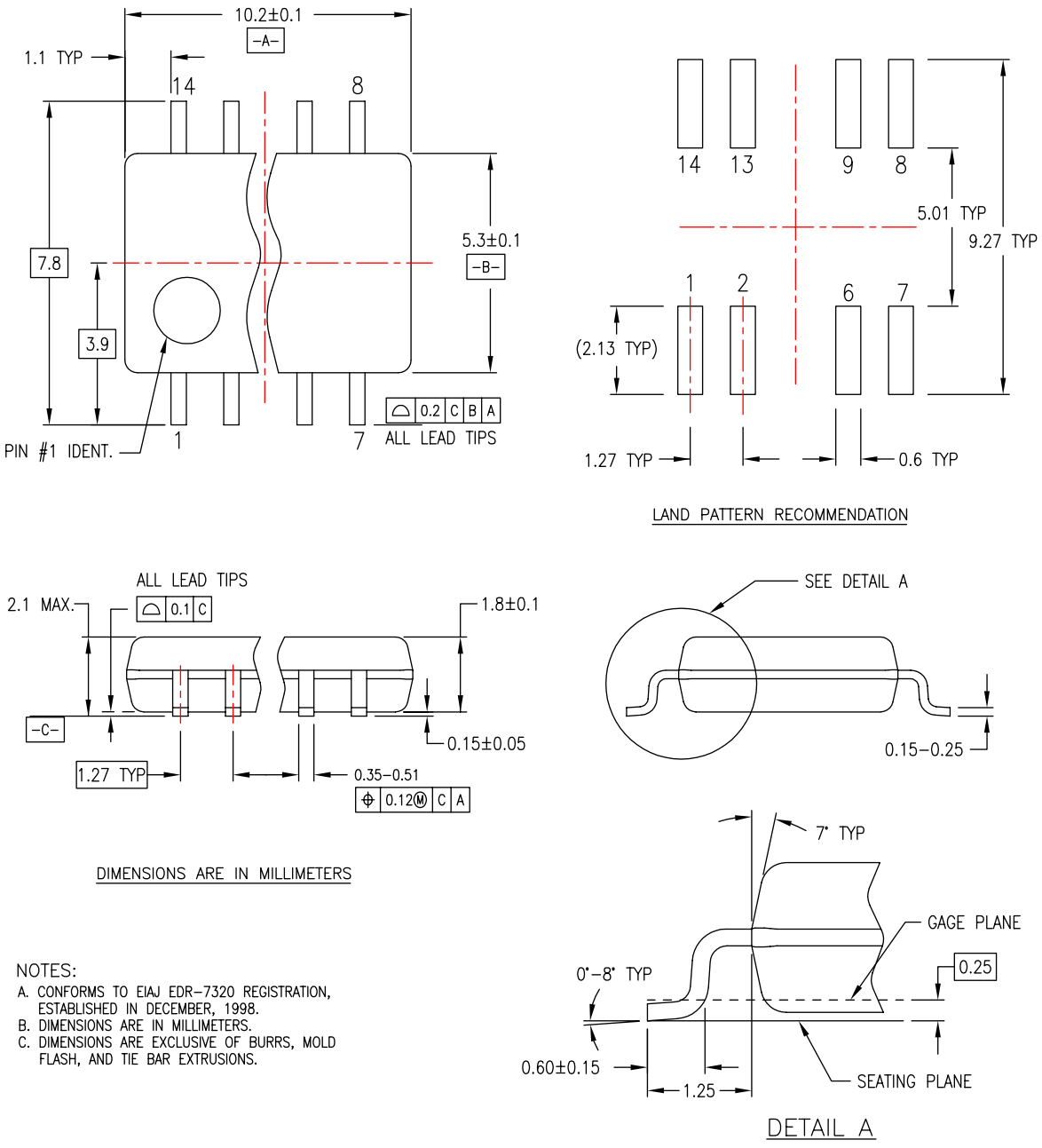
Physical Dimensions (Continued)



NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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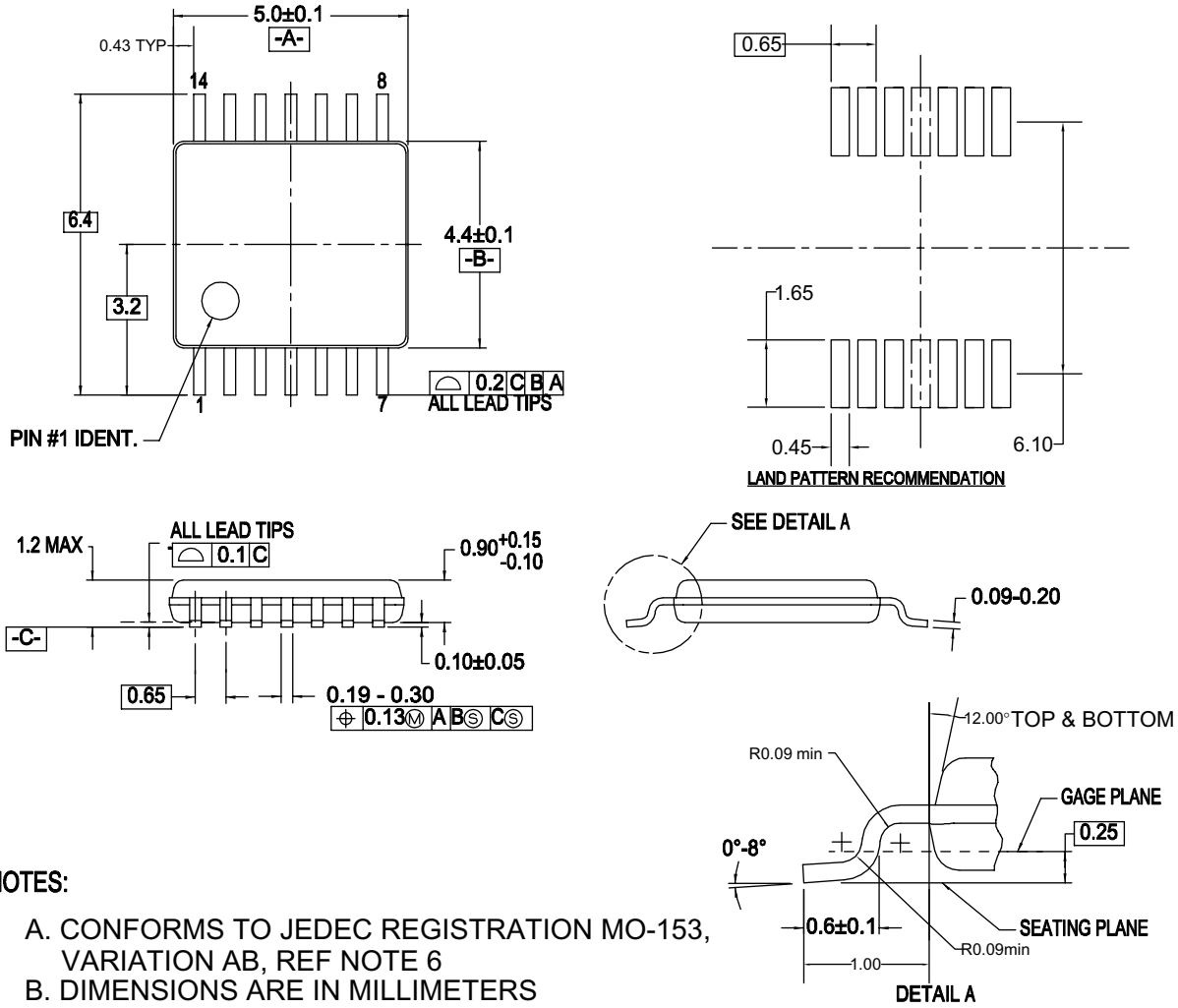
Physical Dimensions (Continued)



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6

B. DIMENSIONS ARE IN MILLIMETERS

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

E. LANDPATTERN STANDARD: SOP65P640X110-14M

F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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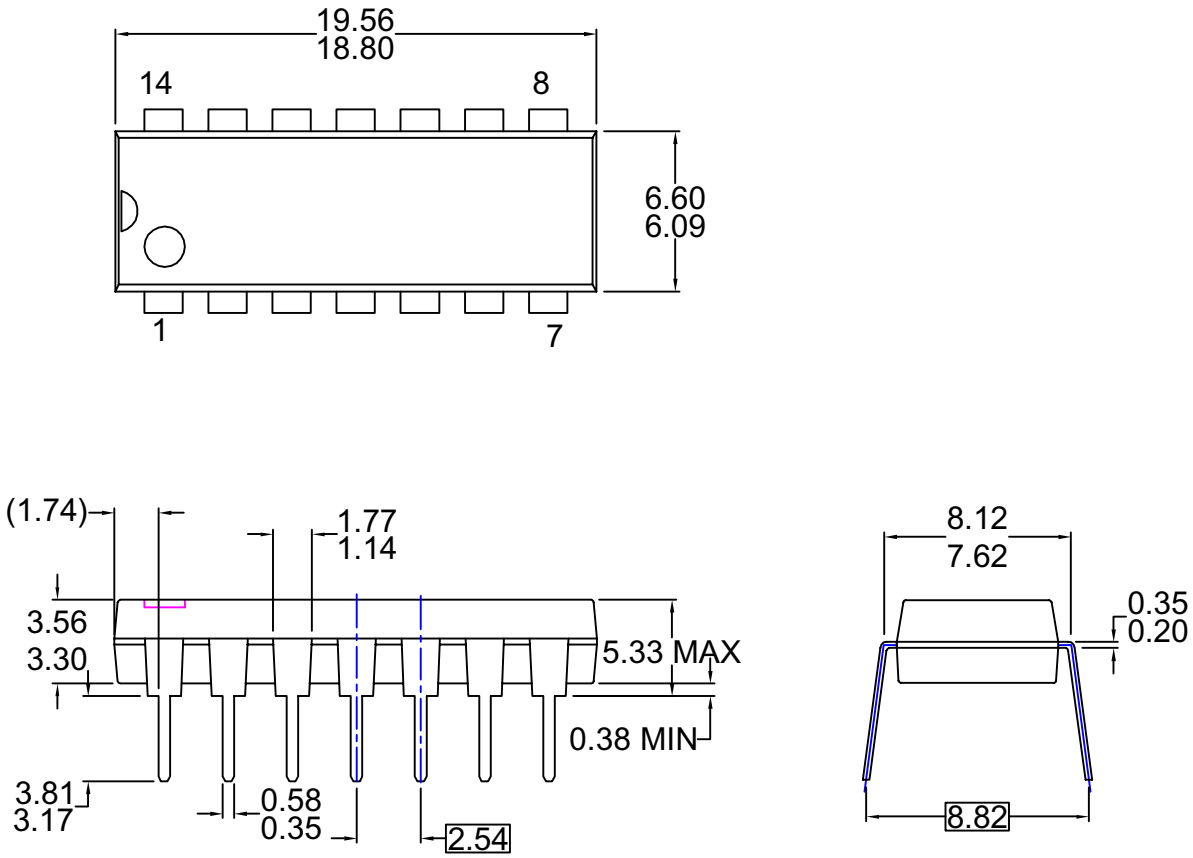
Physical Dimensions (Continued)



NOTES: UNLESS OTHERWISE SPECIFIED

THIS PACKAGE CONFORMS TO

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B) ALL DIMENSIONS ARE IN MILLIMETERS.
DIMENSIONS ARE EXCLUSIVE OF BURRS,

C) MOLD FLASH, AND TIE BAR EXTRUSIONS.

D) DIMENSIONS AND TOLERANCES PER
ASME Y14.5-1994

E) DRAWING FILE NAME: MKT-N14AREV7

Figure 4. 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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